PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Akihiko KINOSHITA	12/13/2007
Takashi KANAO	12/13/2007
Hiroyuki CHIBA	12/13/2007
Tsuyoshi HONMA	12/13/2007
Hirofumi KOUDA	12/13/2007

RECEIVING PARTY DATA

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11960170

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PATENT REEL: 020272 FRAME: 0336

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Total Attachments: 2 source=319812USAssignment#page1.tif source=319812USAssignment#page2.tif

> PATENT REEL: 020272 FRAME: 0337

Docket Number:

ASSIGNMENT	
WHEREAS, I, as a below named inventor, residing at the only one name is listed below) or a joint inventor (if plural names are listed NETWORK SYSTEM, ACCESS MANAGEMENT SERVER, EVENT NAPPLIANCE AND COMPUTER PROGRAM	below) of certain new and useful improvements in
for which application for Letters Patent of the United States of America was	executed by me on the date indicated next to my name
and address;	
AND WHEREAS, Sony Corporation, a Japanese corpor Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring a said application disclosing the invention and in, to and under any Letters Patherefor in the United States and in any and all foreign countries;	all interest in, to and under said invention,
NOW THEREFORE, in consideration of the sum of One Dot the receipt and sufficience of which are hereby acknowledged, I, as a sole or hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assign interest in the said invention, said application, including any divisions and content of the United States, and countries foreign thereto, which may be granterights and/or convention rights under the International Convention for the Protect Relating to Patents, Designs and Industrial Models, and any other international dheres, and to any other benefits accruing or to accrue to me with respect to patents in the United States and countries foreign thereto, and I hereby authorized United States Letters Patent to said ASSIGNEE, as the assignee of the ways of the said United States Letters Patent to said ASSIGNEE, as the assignee of the ways of the said United States Letters Patent to said ASSIGNEE, as the assignee of the ways of the said United States Letters Patent to said ASSIGNEE, as the assignee of the ways of the said ASSIGNEE.	joint inventor as indicated below, begns, and legal representatives, the entire right, title and continuations thereof, and in and to any and all Letters ed for said invention, and in and to any and all priority ction of Industrial Property, Inter-American Convention and agreements to which the United States of America to the filing of applications for patents or securing of ze and request the Commissioner of Patents to issue the
And I further agree to execute all necessary or desirable and lawful ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and lega and without further remuneration, in order to perfect title in said invention, applications and Letters Patent of the United States and countries foreign them.	Il representatives may from time-to-time present to me, modifications, and improvements in said invention,
And I further agree to properly execute and deliver and without further papers for application for foreign patents, for filing subdivisions of said applications of any Letters Patent which may be granted for my aforesaid invention prepare at its own expense;	ication for patent, and or, for obtaining any reissue or
And I further agree that ASSIGNEE will, upon its request, be prov- relating to said application, said invention and said Letters Patent and legal e accessible to me and will testify as to the same in any interference or litigation	equivalents in foreign countries as may be known and
And I hereby covenant that no assignment, sale, agreement or encumber would conflict with this assignment and sale.	brance has been or will be made or entered into which
And I hereby authorize and request my attorney(s) of record in this apthis application in the spaces that follow: Serial Number:	pplication to insert the serial number and filing date of Filing Date:
This assignment executed on the dates indicated below.	
Akihiko KINOSHITA	1 ecember 13 . 2001
Name of first or sole inventor	Execution date of U.S. Patent Application
Tokyo, Japan	
Residence of first or sole inventor	
1 kinike Kinochita	1 scemeel 13 , 2007
Signature of first or sole inventor	Date of this assignment

PATENT REEL: 020272 FRAME: 0338

Takashi KANAO	December 13. 2007
Name of second inventor	Execution date of U.S. Patent Application
Tokyo, Japan	
Residence of second inventor	
Takashi Kanao	Docember 13. 2007
Signature of second inventor	Date of this assignment
	Ç
Hiromyki CUIDA	December 13 2007
Hiroyuki CHIBA Name of third inventor	Execution date of U.S. Patent Application
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Residence of third inventor	
Vinoguhi Chilon	Lecember 13 2007
Signature of third inventor	Date of this assignment
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Tsuyoshi HONMA	December 13 2007
Name of fourth inventor	Execution date of U.S. Patent Application
Chiba, Japan	
Residence of fourth inventor	
Luyahi lobmu	December 13 2007
Signature of fourth inventor	Date of this assignment
Hirofumi KOUDA	
Name of fifth inventor	Execution date of U.S. Patent Application
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Residence of fifth inventor	
Hirofumi Koda.	December 18 2007
Signature of fifth inventor	Date of this assignment

PATENT REEL: 020272 FRAME: 0339

RECORDED: 12/19/2007